

Tgrease[™] 2500 High Performance TIM



PRODUCT DESCRIPTION

Tgrease [™] 2500 is a silicone-free thermal grease for use in high performance processing components like CPU's, GPU's, custom ASICs, Multi-Chip, SoC, etc. With a high thermal conductivity of 3.8 W/mK, Tgrease [™] 2500 thoroughly wets out thermal surfaces to create very low thermal resistance. Tgrease [™] 2500 eliminates the migration issues of silicone-based grease to create superior reliability. Tgrease [™] 2500 is ideal for situations where automatic dispensing and screen- printing are required.

Tgrease[™] 2500 is non-toxic and environmentally safe. Tgrease[™] 2500 is available in 1kg (pint container), 3kg (quart container), and 10kg (gallon container) or custom packaged in syringes for automated applications.

FEATURES & BENEFITS

- 3.8 W/mK bulk thermal conductivity
- Non silicone formulation
- Fully characterized long term reliability
- Unique formulas will not harden, dry out, settle or oxidize.
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH
- Easy rework

AVAILABILITY

 Cans, Pails, Syringes and Cartridges 10 kg: A14259-03
1 kg can: A14259-01
½ kg can: A14259-05
50cc syringes: A14399-03
600cc cartridges: A14259-10

MARKETS

- Semiconductor Packaging
- · Graphics Card
- Notebooks
- Desktops
- Servers
- IGBTs
- Automotive
- Memory Modules

STORAGE CONDITIONS

- Store in original packaging
- Store at 20-35°C & maximum 50% RH
- Shelf Life once opened: 1 year from date of mix when stored at above conditions
- Shelf Life unopened: 2 year from date of mix when stored at above conditions

TYPICAL PROPERTIES

PROPERTY	VALUE	TEST METHOD
Construction	Silicone Free Thermal Grease	N/A
Color	White	Visual
Density	3.4 g/cc	Helium Pycnometer
Bulk Thermal Conductivity	3.8 W/m-K	Hot Disk
Thermal Resistance 10 psi & 70°C 50 psi & 70°C	0.15°C-cm²/W 0.13°C-cm²/W	ASTM D5470
Operating Temperature Range	-55°C to 150°C	Laird Test Method
Viscosity	2,500,000cP	Brookfield Viscometer - TF spindle at 2rpm (helipath) @ 23°C
Minimum Bondline Thickness	50µm	Laird Test Method
Outgassing (TML)	0.91%	E595
Outgassing (CVCM)	0.15%	E595
Dielectric Constant	5.7@1KHz / 5.6@1MHz	ASTM D150
Volume Resistivity	3.5x10 ¹² Ω-cm	ASTM D991
UL Recognition	V-0	UL94

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